

** TEXAS INSTRUMENTS Bill of Materials

TI DESIGNS

TIDA-00230

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	!PCB1		Printed Circuit Board	Any	TIDA00230			
2	1	C1	0.47uF	X7R, 0603	MuRata	GRM188R71E474KA12D		0603	
3	3	C2, C5, C8	0.1uF	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402	MuRata	GRM155R71C104KA88D		0402	
4	3	C3, C4, C9	1uF	CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603	MuRata	GRM188R71C105KA12D		0603	
5	1	C6	100uF	CAP, CERM, 100uF, 10V, +/-20%, X5R, 1206_190		C3216X5R1A107M160AC		1206	
6	1	C10	39pF	CAP, CERM, 39pF, 50V, +/-5%, C0G/NP0, 0402	MuRata	GRM1555C1H390JA01D		0402	
7	3	D1, D2, D5		523F	Comchip Technology	CDBU0130L		sod523	
8	2	D3, D4	orange	LED, Orange, SMD	Rohm	SML-311DTT86		0603	
9	6	FID1, FID2, FID3, FID4, FID5, FID6		Fiducial mark. There is nothing to buy or mount.	N/A	N/A			
10	2	J1, J3		Header, 50mil, 4x1, R/A, TH	Sullins Connector Solutions	GRPB041VWCN-RC			
11	5	R1, R4, R7, R8, R10	OR	RES, 0 ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04020000Z0ED		0402	
12	2	R2, R3		RES, 4.75k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04024K75FKED		0402	
13	2	R5, R6		RES, 1.00k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04021K00FKED		0402	
14	1	R11	47k	RES, 47k ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW040247K0JNED		0402	
15	1	U1		Mixed Signal Microcontroller, RGZ0048B	Texas Instruments	MSP430FR5969IRGZ		RGZ	
16	1	U2		DYNAMIC NFC INTERFACE TRANSPONDER, PW0014A	Texas Instruments	RF430CL330HCPW		CPW	
17	2	U5, U6		ESD in 0402 Package with 10 pF Capacitance and 6 V Breakdown, 1 Channel, -40 to +125 degC, 2- pin X2SON (DPY), Green (RoHS & no Sb/Br)	Texas Instruments	TPD1E10B06DPYR		DPYR	

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